



标准&定制开关连接器产品制造商
DONG GUAN XI BANG ELECTRONICS CO., LTD.

规格书

SPECIFICATION

CUSTOMER NAME	客户名称:	_____
CUSTOMER NO.	客户编号:	_____
SERIES	系列:	LED模块系列
MODEL NO.	型号:	XB-LED series
DRAWING NO.	图形号:	XB LED module series

If specification of this product meets your request, please confirm all the items of it and return to us with signature and stamp, it will be basis of our production and record. Thanks your cooperation in advance!

若此产品规格符合贵司要求，敬请确认此规格书内所有项目
并签名和盖章后回传给我司，以作我司产品制作之
依据和存档之用，多谢合作！

EXAMINE & APPROVAL 审批

APPROVE 接受	NOT APPROVE 不接受
SIGNATURE 签署 STAMP 盖章 DATE 日期	

PREPARED BY. 制表人	CHECKED BY. 校对	APPROVED BY. 审核	APPROVAL BY. 批准
<div style="border: 1px solid red; padding: 2px; display: inline-block;">研发部</div> <div style="border: 1px solid red; padding: 2px; display: inline-block;">戴海明</div> <div style="border: 1px solid red; padding: 2px; display: inline-block;">2022. 06. 08</div>	<div style="border: 1px solid red; padding: 2px; display: inline-block;">品质部</div> <div style="border: 1px solid red; padding: 2px; display: inline-block;">黄自清</div> <div style="border: 1px solid red; padding: 2px; display: inline-block;">2022. 06. 08</div>	<div style="border: 1px solid red; padding: 2px; display: inline-block;">工程部</div> <div style="border: 1px solid red; padding: 2px; display: inline-block;">庞军</div> <div style="border: 1px solid red; padding: 2px; display: inline-block;">2022. 06. 08</div>	<div style="border: 1px solid red; padding: 2px; display: inline-block;">总经办</div> <div style="border: 1px solid red; padding: 2px; display: inline-block;">吴量</div> <div style="border: 1px solid red; padding: 2px; display: inline-block;">2022. 06. 08</div>

东莞市溪榜电子有限公司

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Dong Guan XB Electronics Co., Ltd

AccountNumber: 705540238
BankName: Citibank N. A., HongKongBranch
Country/Region: Hong Kong
BankCode: 006
BankAddress: 3GardenRoad, Central, Hong Kong
SWIFT/BIC: CITIHKHX (CITIHKHXXXX*If 11 characters are required)

MAiL: HK@ALPSR.CN XB@ALPSR.CN XB@ALPSR.COM
Quality core! Afterburner for Made in China!

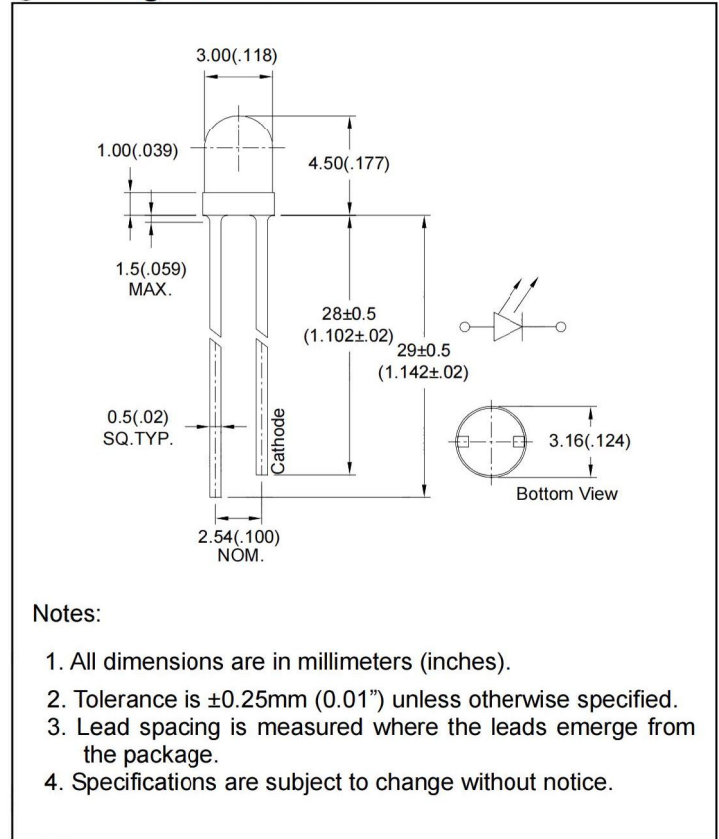
● Features:

1. Chip material: GaP/GaP
2. Emitted color : Bright Red
3. Lens Appearance : Red Diffused
4. Low power consumption.
5. High efficiency.
6. Versatile mounting on P.C. Board or panel.
7. Low current requirement.
8. 3mm diameter package.
9. This product don't contained restriction substance, compliance RoHS standard.

● Applications:

1. TV set
2. Monitor
3. Telephone
4. Computer
5. Circuit board

● Package dimensions:



● Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Rating	Unit
Power Dissipation	Pd	40	mW
Forward Current	I _F	30	mA
Peak Forward Current* ¹	I _{FP}	50	mA
Reverse Voltage	V _R	5	V
Operating Temperature	Topr	-40°C~85°C	
Storage Temperature	Tstg	-40°C~100°C	

*¹Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.

● Electrical and optical characteristics(Ta=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F=20mA$	-	2.3	2.6	V
Luminous Intensity	I_v	$I_F=20mA$	-	2.0	-	mcd
Reverse Current	I_R	$V_R=5V$	-	-	100	μA
Peak Wave Length	λ_p	$I_F=20mA$	-	700	-	nm
Dominant Wave Length	λ_d	$I_F=20mA$	-	650	-	nm
Spectral Line Half-width	$\Delta \lambda$	$I_F=20mA$	-	100	-	nm
Viewing Angle	$2\theta_{1/2}$	$I_F=20mA$	-	45	-	deg

● Typical Electro-Optical Characteristics Curves

Fig.1 Relative intensity vs. Wavelength

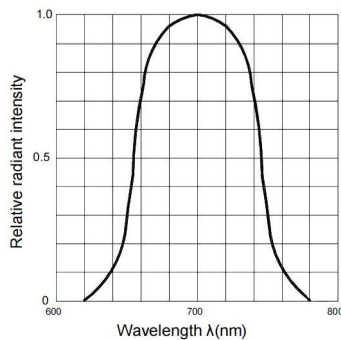


Fig.2 Forward current derating curve vs. Ambient temperature

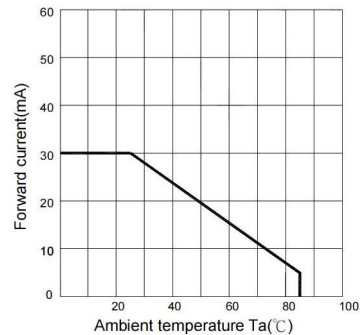


Fig.3 Forward current vs. Forward voltage

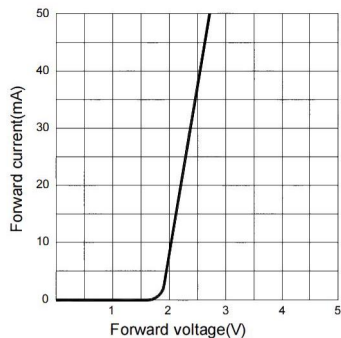


Fig.4 Relative luminous intensity vs. Ambient temperature

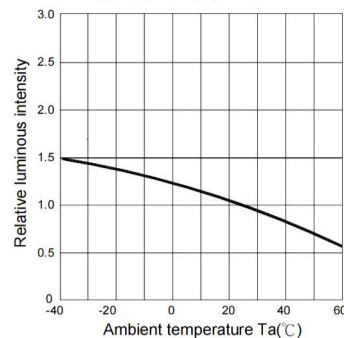


Fig.5 Relative luminous intensity vs. Forward current

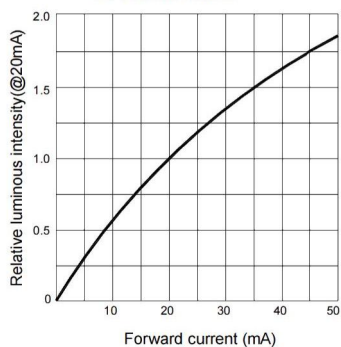
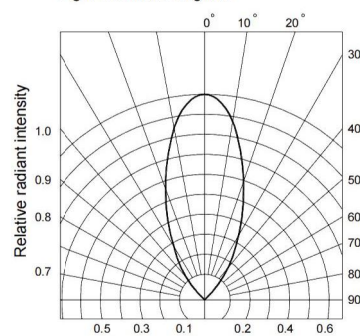


Fig.6 Radiation diagram





● Bin Limits

1. Intensity Bin Limits (At $I_F = 20\text{mA}$)

Bin Code	Min. (mcd)	Max. (mcd)
C	0.7	1.0
D	1.0	1.6
E	1.6	2.4
F	2.4	3.7
G	3.7	5.5

Bin : x

↑
——— Intensity bin code

NOTES:1.Tolerance of measurement of luminous intensity.

:±15%



● Reliability Test

Classification	Test Item	Reference Standard	Test Conditions	Result
Endurance Test	Operation Life	MIL-STD-750:1026 MIL-STD-883:1005 JIS-C-7021 :B-1	I _F =20mA Ta=+25°C±5°C Test time=1,000hrs	0/32
	High Temperature High Humidity Storage	MIL-STD-202:103B JIS-C-7021 :B-11	Ta=+85°C±5°C RH=90%-95% Test time=240hrs	0/32
	High Temperature Storage	MIL-STD-883:1008 JIS-C-7021 :B-10	High Ta=+85°C±5°C Test time=1,000hrs	0/32
	Low Temperature Storage	JIS-C-7021 :B-12	Low Ta=-45°C±5°C Test time=1,000hrs	0/32
Environmental Test	Temperature Cycling	MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1010 JIS-C-7021 :A-4	Ta: +85°C (30min) ~ +25°C (5min) ~ -45°C (30min) ~ +25°C (5min) Test Time : 70min/ctcle 10cycle	0/32
	Thermal Shock	MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1011	-45°C±5°C ~+85°C±5°C 20min 20min Test Time=10cycle	0/32
	Solder Resistance	MIL-STD-202:201A MIL-STD-750:2031 JIS-C-7021 :A-1	Preheating : 120°C ,within 120-180 sec. Operation heating : 255°C±5°C within 5 sec.260°C (Max)	0/32
	Solderability	MIL-STD-202F:208D MIL-STD-750D:2026 MIL-STD-883D:2003 JIS C 7021:A-2	T.sol=230±5°C Dwell Time=5±1secs	0/32

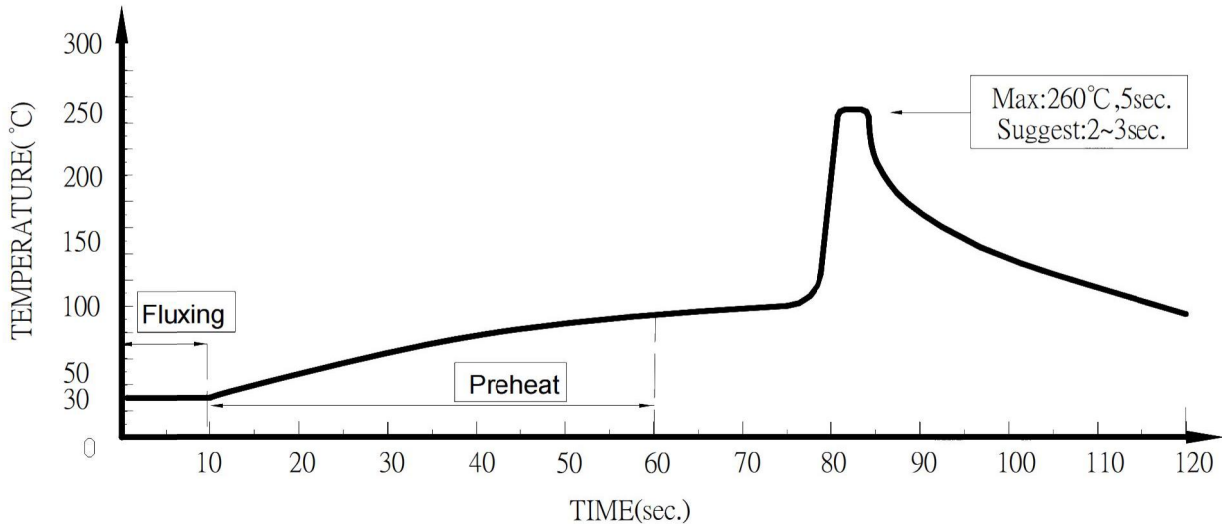
● Judgment criteria of failure for the reliability

Measuring items	Symbol	Measuring conditions	Judgment criteria for failure
Forward voltage	V _F (V)	I _F =20mA	Over U ¹ x1.2
Reverse current	I _R (uA)	V _R =5V	Over U ¹ x2
Luminous intensity	I _v (mcd)	I _F =20mA	Below S ¹ X0.5

Note: 1. U means the upper limit of specified characteristics. S means initial value.

2. Measurement shall be taken between 2 hours and after the test pieces have been returned to normal ambient conditions after completion of each test.

● Dip Soldering



1. Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature, especially during soldering
2. DIP soldering and hand soldering should not be done more than one time.
3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temperature.
4. Avoid rapid cooling during temperature ramp-down process
5. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

● IRON Soldering

300°C Within 3 sec., One time only.

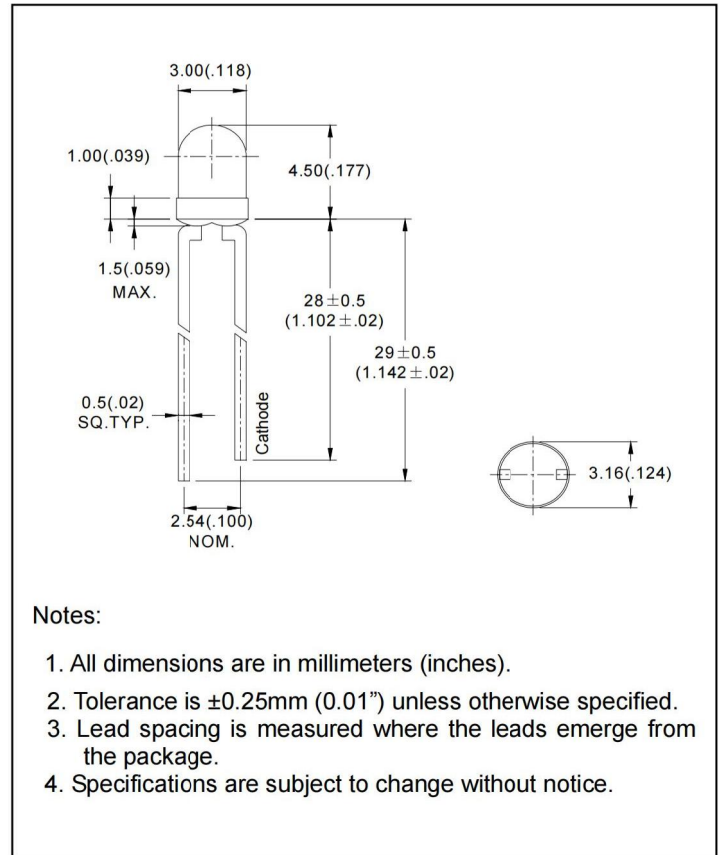
● Features:

1. Chip material: GaP /GaP
2. Emitted color : Green
3. Lens Appearance : Green Diffused
4. Low power consumption.
5. High efficiency.
6. Versatile mounting on P.C. Board or panel.
7. Low current requirement.
8. 3mm diameter package
9. This product don't contained restriction substance, compliance ROHS standard.

● Applications:

1. TV set
2. Monitor
3. Telephone
4. Computer
5. Circuit board

● Package dimensions



● Absolute maximum ratings($T_a=25^\circ\text{C}$)

Parameter	Symbol	Rating	Unit
Power Dissipation	P_d	80	mW
Forward Current	I_F	30	mA
Peak Forward Current* ¹	I_{FP}	150	mA
Reverse Voltage	V_R	5	V
Operating Temperature	T_{opr}	$-40^\circ\text{C} \sim 85^\circ\text{C}$	
Storage Temperature	T_{stg}	$-40^\circ\text{C} \sim 100^\circ\text{C}$	
Soldering Temperature	T_{sol}	260°C max (for 5 seconds)	
Hand Soldering Temperature	T_{sol}	350°C max(for 3 seconds)	

*¹Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.

● Electrical and optical characteristics(Ta=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F=20mA$	-	2.2	2.6	V
Luminous Intensity	I_v	$I_F=20mA$	-	35	-	mcd
Reverse Current	I_R	$V_R=5V$	-	-	100	μA
Peak Wave Length	λ_p	$I_F=20mA$	-	568	-	nm
Dominant Wave Length	λ_d	$I_F=20mA$	560	-	576	nm
Spectral Line Half-width	$\Delta \lambda$	$I_F=20mA$	-	30	-	nm
Viewing Angle	$2\theta_{1/2}$	$I_F=20mA$	-	45	-	deg

● Typical electro-optical characteristics curves

Fig.1 Relative intensity vs. Wavelength

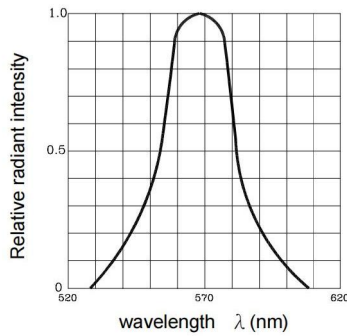


Fig.2 Forward current derating curve vs. Ambient temperature

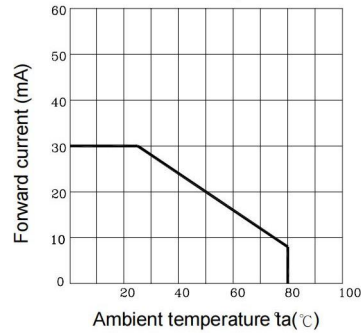


Fig.3 Forward current vs. Forward voltage

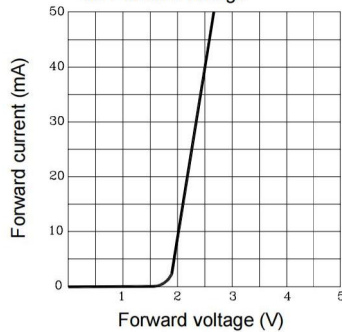


Fig.4 Relative luminous intensity vs. Ambient temperature

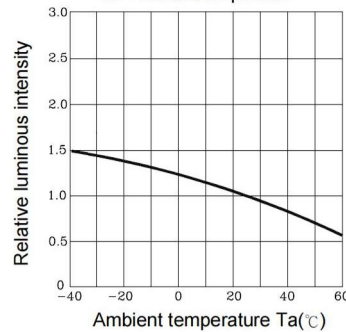


Fig.5 Relative luminous intensity vs. Forward current

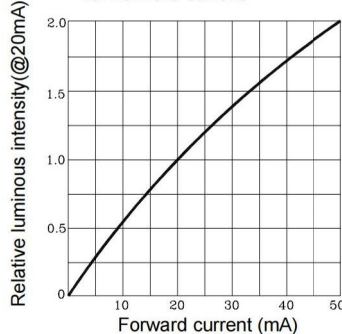
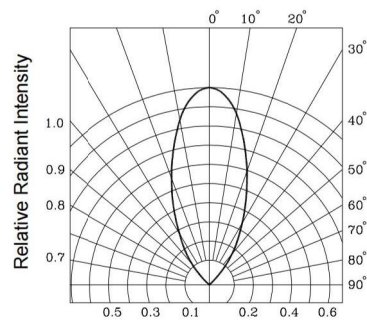


Fig.6 Radiation diagram



● Bin Limits

1. Intensity Bin Limits (At $I_F = 20\text{mA}$)

Bin Code	Min. (mcd)	Max. (mcd)
K	12.3	18.5
L	18.5	28
M	28	42
N	42	63
P	63	94

● Bin : x



NOTES: 1. Tolerance of measurement of luminous intensity.

: $\pm 15\%$

● DIP soldering (Wave Soldering)

Preheating : 120°C , within 120~180 sec.

Operation heating : $255^\circ\text{C} \pm 5^\circ\text{C}$ within 5 sec. 260°C (Max)

Gradual Cooling (Avoid quenching).

